

# PRODUCT DATA SHEET



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Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO\_questions@jgsemi.com.

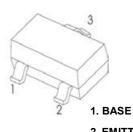


**2SD2142** 

SOT-23 Plastic-Encapsulate Transistors

#### FEATURES

- Darlington Connection for a High h<sub>FE</sub>
- High Input Impedance



SOT - 23

2. EMITTER 3. COLLECTOR

#### MAXIMUM RATINGS (T<sub>a</sub>=25°C unless otherwise noted)

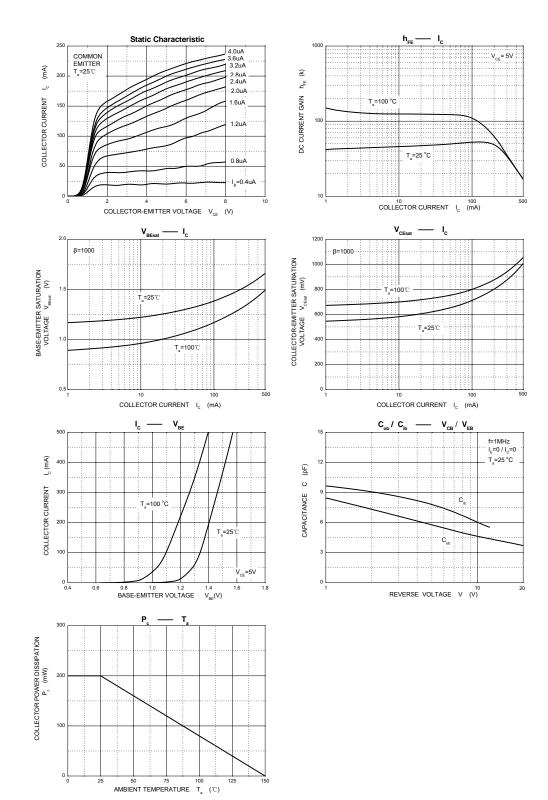
Symbol	Parameter	Value	Unit
V <sub>сво</sub>	Collector-Base Voltage	40	V
V <sub>CEO</sub>	Collector-Emitter Voltage	32	V
V <sub>EBO</sub>	Emitter-Base Voltage	12	V
Ιc	Collector Current	300	mA
Pc	Collector Power Dissipation	200	mW
R <sub>OJA</sub>	Thermal Resistance From Junction To Ambient	625	°C/W
T <sub>J</sub> ,T <sub>stg</sub>	Operation Junction and Storage Temperature Range	-55~+150	°C

#### ELECTRICAL CHARACTERISTICS (T<sub>a</sub>=25<sup>°</sup>C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Мах	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =100μA, I <sub>E</sub> =0	40			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =10mA, I <sub>B</sub> =0	32			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =100μA, I <sub>C</sub> =0	12			V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> =30V, I <sub>E</sub> =0			0.1	μA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =12V, I <sub>C</sub> =0			0.1	μA
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> =3V, I <sub>C</sub> =100mA	5000			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =200mA, I <sub>B</sub> =0.2mA			1.4	V
Transition frequency	fT	V <sub>CE</sub> =5V,I <sub>C</sub> =10mA, f=100MHz		200		MHz
Collector output capacitance	C <sub>ob</sub>	V <sub>CB</sub> =10V, I <sub>E</sub> =0, f=1MHz		2.5		pF

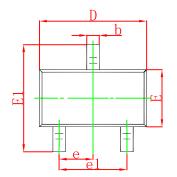


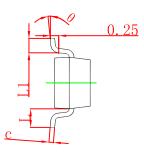
## 2SD2142

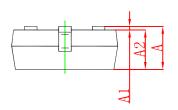




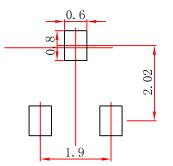
## **2SD2142**







Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950	) TYP	0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550	) REF	0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	6°	



Note:

Controlling dimension:in millimeters.
General tolerance:± 0.05mm.
The pad layout is for reference purposes only.





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